Appl. No. 10/601,351 Amdt. dated December 1, 2004 Amendment under 37 CFR 1.116 Expedited Procedure Examining Group

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

14-19. (Withdrawn)

- 20. (Currently Amended): An integrated circuit, comprising:
- a logic inverter comprising:
 - an n-channel field effect transistor;
 - a p-channel field effect transistor;
 - a gate, formed in a layer of polysilicon; and
- a connection between a drain of the p-channel field effect transistor and a drain of the n-channel field effect transistor formed in said same layer of polysilicon, wherein the polysilicon comprising said gate is coplanar with the polysilicon comprising said connection between said drain of the p-channel field effect transistor and said drain of the n-channel field effect transistor.
 - 21. (Cancelled):
- 22. (Previously Presented): The integrated circuit as described in claim 20, further comprising:
 - a first layer of metallization; and
- a second layer of metallization, wherein the second layer of metallization comprises substantially no local interconnect.
- 23. (Previously Presented): The integrated circuit as described in claim 22, wherein said second layer of metallization comprises no local interconnect.

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- 24. (Previously Presented): The integrated circuit as described in claim 20, further comprising:
 - a plurality of MACROs;
 - a fist first layer of metallization; and
 - a second layer of metallization interconnecting said plurality of MACROs.
 - 25. (Cancelled)
- 26. (Previously Presented): The integrated circuit as described in claim 24, further comprising, no local interconnect within said second layer of metallization in at least one of said MACROs.
- 27. (Previously Presented): The integrated circuit as described in claim 24, further comprising, no local interconnect within said second layer of metallization in a plurality of said MACROs.
- 28. (Previously Presented): The integrated circuit as described in claim 24, further comprising, no local interconnect within said second layer of metallization in all of said plurality of MACROs.
- 29. (Previously Presented): The integrated circuit as described in claim 24, wherein at least one of said MACROs is comprised by a standard cell array of the integrated circuit.
- 30. (Previously Presented): The integrated circuit as described in claim 29, wherein said standard cell array comprises a row pitch and at least one MACRO has a row pitch equivalent to the row pitch of said standard cell array.